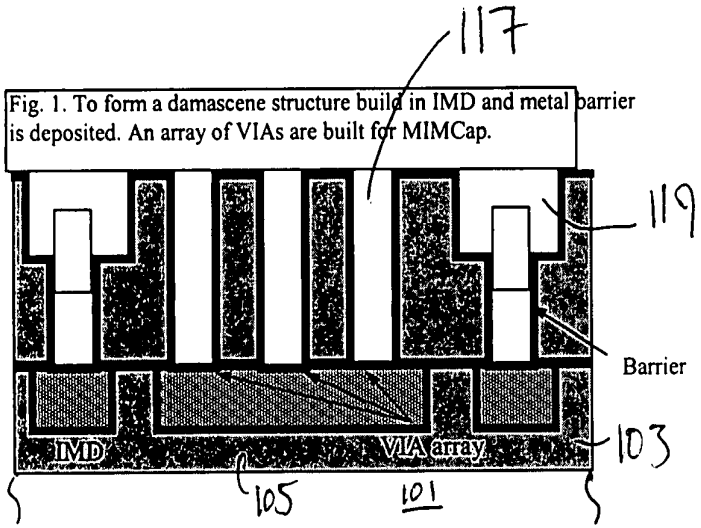


Fig. 1. To form a damascene structure build in IMD and metal barrier is deposited. An array of VIAs are built for MIMCap.

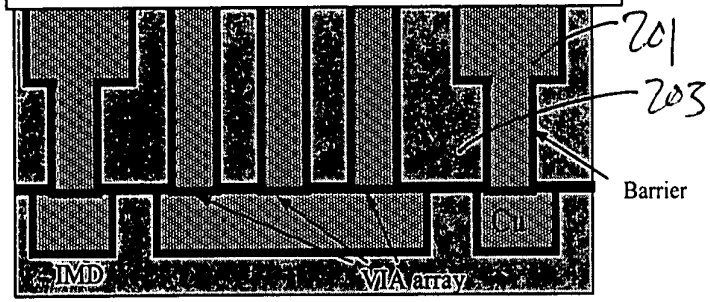


Fig. 2 Cu seed, Plating and CMP are done the same way as conventional dual-damascene Cu interconnect processes

Fig. 3 A layer of dielectric is deposited followed by a lithography Patterning to open the area where MIMCap need to be built.

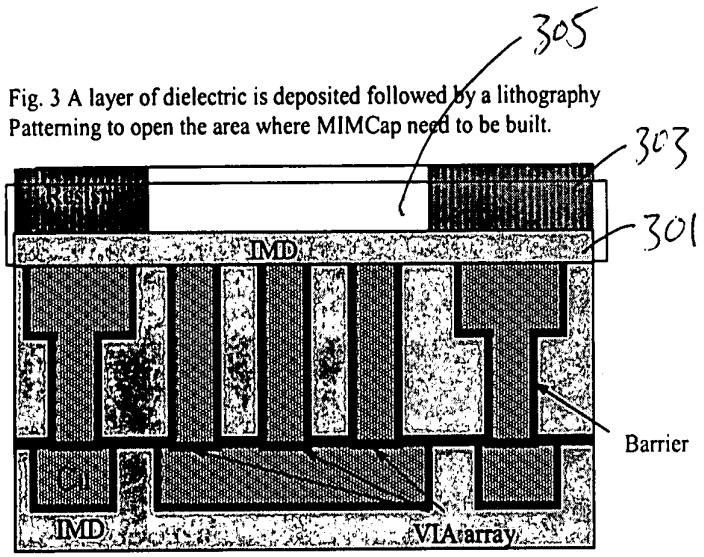


Fig. 4 To selectively etch dielectric and strip the residual resist This process leaves Cu VIAs stand alone

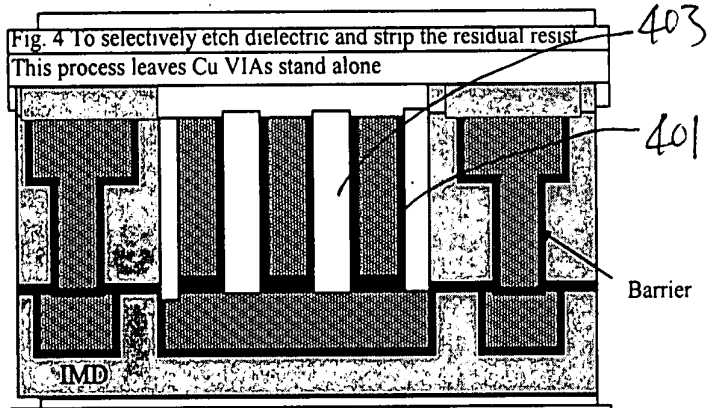
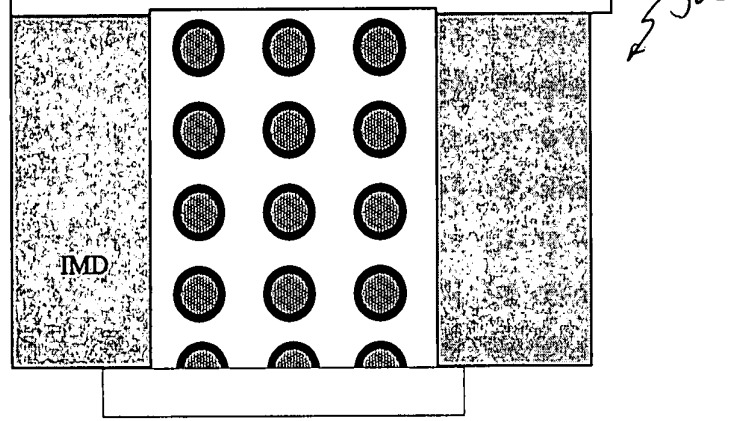


Fig. 5 Top-view of Fig. 4.



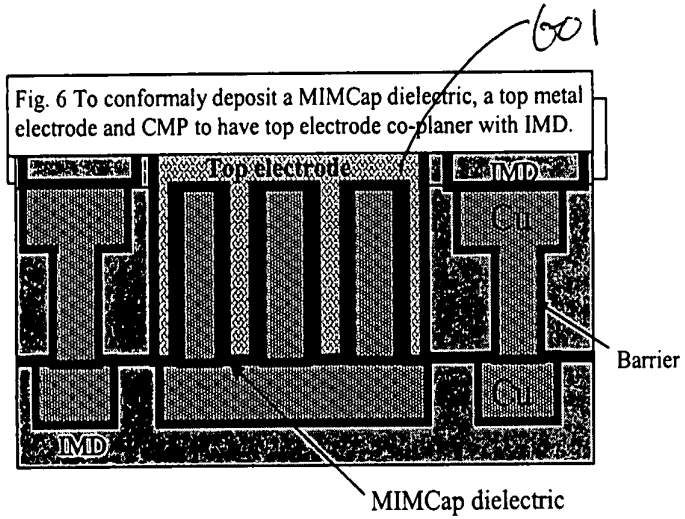


Fig. 6 To conformaly deposit a MIMCap dielectric, a top metal electrode and CMP to have top electrode co-planer with IMD.